



1722  
PATENT  
450100-03654

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Katsuhiro DOI et al.  
Serial No. : 09/996,518  
For : MOLDING DIE APPARATUS AND MOLDING METHOD  
Filed : November 29, 2001  
Examiner : Luk, Emmanuel S.  
Art Unit : 1722

745 Fifth Avenue  
New York, NY 10151

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 25, 2005.

Lecanne Lawlor

(Typed Name of Person Mailing Paper or Fee)

Signature

January 25, 2005

Date of Signature

**AMENDMENT**

Commission for Patents  
Box 1450  
Alexandria, VA 22313-1450

Sir:

Responsive to the Official Action mailed September 2, 2004, please amend the  
above-identified application as follows:

01/31/2005 KBETEMA1 00000027 09996518

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